WHAT IS CLAIMED IS:

1. A polishing composition comprising polymer particles and inorganic particles in an aqueous medium, wherein the inorganic particles have an average particle size of from 5 to 170 nm, and wherein an average particle size Dp (nm) of said polymer particles and an average particle size Di (nm) of said inorganic particles satisfy the following formula (1):

$$Dp \leq Di + 50 \text{ nm} \qquad (1) .$$

2. The polishing composition according to claim 1, wherein the polymer particles are made of a thermoplastic resin.

3. The polishing composition according to claim 1, wherein the polymer particles are made of a resin having a glass transition temperature of 200°C or less.

4. The polishing composition according to claim 1, wherein the polymer particles are made of a resin having a degree of cross-linking of 50 or less.

5. The polishing composition according to claim 1, wherein the inorganic particles are colloidal silica.

6. The polishing composition according to claim 1, wherein a ratio of Cp/Ci is from 0.03 to 2, wherein Cp is a content of the polymer particles in the polishing composition and Ci is a content of the inorganic particles in the

polishing composition.

7. A polishing process for a substrate to be polished comprising polishing the substrate to be polished with the polishing composition as defined in any one of claims 1 to 6.

8. A process for improving a rate for polishing a substrate to be polished with the polishing composition as defined in any one of claims 1 to 6.